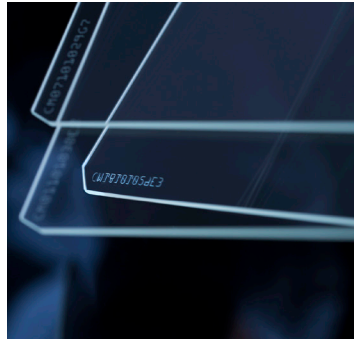


CORNING



Carrier Solutions Standard Glass Carriers

Applications

- Glass carriers for temporary bonding in advanced semiconductor packaging processes such as Silicon wafer thinning and fan-out level processing

Benefits

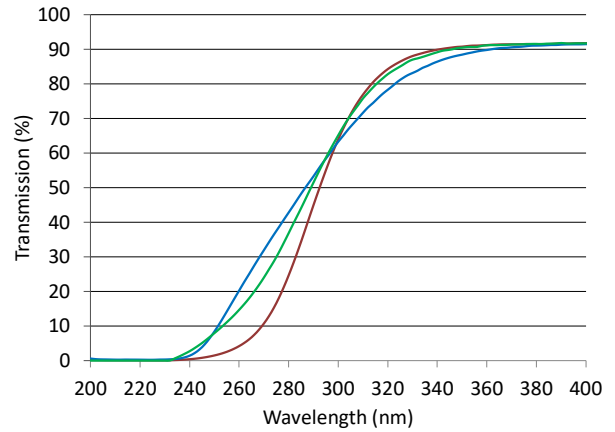
- Tunable CTE and mechanical properties to meet various semiconductor process requirements
- Scalable form factor in both wafer and panel formats
- Low TTV and warp
- Optically transparent enabling UV or IR based debond processes and laser mark serialization
- Excellent chemical durability conducive to semiconductor process environments

Property	SG 3.4	SG 7.8	SG 9.0
CTE (0-300°C, x10 ⁻⁶ /°C)	3.4	7.8	9.0
Density (g/cm ³)	2.38	2.39	2.42
Young's Modulus (GPa)	73.6	69.3	65.8
Shear Modulus (GPa)	30.1	28.5	26.0
Vicker's Hardness (kgf/mm ²) 200gm load	640	534	489
Annealing Point (°C)	722	628	646
Strain Point (°C)	669	574	596
Refractive Index (589.3nm)	1.51	1.50	1.49

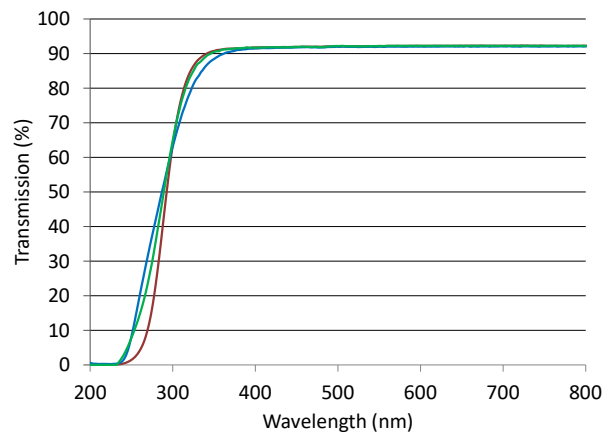
Options and Features

CTE Offerings	3.4 x10 ⁻⁶ /°C – 10x10 ⁻⁶ /°C
Form Factors	Wafers: 100mm – 450mm Panels: Up to 600mm x 600mm
Thickness	Wafers: 0.4mm – 1.1mm Panels: 0.7mm - 2.0mm
Edge Beveling	Radius (R) Type and Chamfer (C)
Surface Roughness	< 1.0nm
Features	Wafers: Semi-standard notch/flat Panels: Orientation corner profiles
Surface ID Marking	Semi-standard or custom

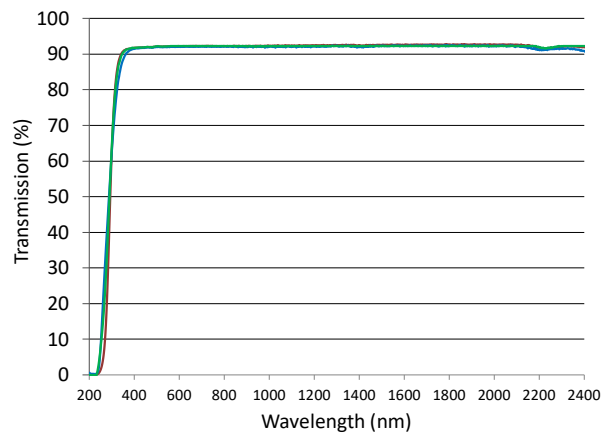
UV Transmission



Visible Transmission



IR Transmission



0.7mm thickness

■ SG 3.4 ■ SG 7.8 ■ SG 9.0

Precision Glass
Solutions

CORNING

Superior Standards

Carrier Solutions

Glass is highly transparent, has the ability to custom-match CTE, and has superior surface quality, thickness, and edge strength, making it an excellent material of choice for carrier substrates used in semiconductor manufacturing.

Corning Carrier Solutions offers precision glass carrier substrates in a wide range of CTEs with quick sampling to reduce customer development time. All samples are high-quality, optical-grade material with exceptionally low total thickness variation and a pristine surface.

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